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Mund et al.

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(54) **PROCESS FOR PRODUCING COPY PROTECTION FOR AN ELECTRONIC CIRCUIT**

(75) Inventors: **Dietrich Mund**, Oberstüssbach (DE);
Jürgen Leib, Freising (DE)

(73) Assignee: **Schott AG**, Mainz (DE)

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See application file for complete search history.

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Primary Examiner—W. David Coleman

(74) *Attorney, Agent, or Firm*—Ohlandt, Greeley, Ruggiero & Perle, L.L.P.

(57) **ABSTRACT**

Processes for producing copy protection for an integrated circuit are provided. To avoid unauthorized copying of an integrated circuit, an effective and reliable copy protection are provided. The process includes the steps of providing a substrate that has semiconductor structures on at least a first side of the substrate, providing a material for coating the substrate, and coating the substrate with a copy-protect layer. In one embodiment, the copy-protect layer is produced by applying a silicate glass by evaporation coating. Thus, an etching process that dissolves the copy-protect layer also attacks the substrate so that the semiconductor structures are at least partially destroyed.

35 Claims, 9 Drawing Sheets

